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**CONNECTION BETWEEN SEMICONDUCTOR
UNIT AND DEVICE CARRIER**

ABSTRACT OF THE DISCLOSURE

5 The present invention provides methods / interconnection portions for connecting at least a semiconductor unit such as chip to at least a device carrier (such as lead frame) lacking good mechanism for limiting solder flowing of melted metal. The methods are characterized by forming at least a device carrier bump jutting out from a metal surface of the device carrier lacking good mechanism thereon for limiting solder
10 flowing of melted metal, and forming at least a chip bump which melts for the device carrier bump to approach the electrode of the chip and have an end on the electrode of the chip. The chip bump melts to surround and adhere to the device carrier bump, and to have one end on the metal surface of the device carrier, resulting in an
15 interconnection portion including a first part and a second part both having one end on the metal surface and another end on the chip.